APR 1 6 2002

# AMENDMENT TRANSMITTAL LETTER

Docket No. M4065.0166/P166-A

1765

Filing Date Application No. Examiner Art Unit 09/643,946 August 23, 2000 L. Vinh

Applicant(s): Kevin J. Torek et al.

Invention: ACID BLEND FOR REMOVING ETCH RESIDUE

#### TO THE COMMISSIONER FOR PATENTS

Transmitted herewith is an Amendment Under 37 CFR 1.116 in the above-identified application.

The fee has been calculated as shown below.

		CLAIM	S AS AMEND	DED	1
	Claims Remaining After Amendment	Highest Number Previously Paid	Number Extra Claims Present	Rate	950
Total Claims	19	- 22 =	0	X	, Cx
ndependent Claims	3	- 3 =	0	х	7. APR 12
Multiple Depen	dent Claims (ch	eck if applicabl	e)		72
Other fee (please specify):					
TOTAL ADDITIONAL FEE FOR THIS AMENDMENT:					0
x Large Entity Small Entity					ity
No addition	al fee is require	d for this Ame	ndment.		
	ge Deposit Acc			the amount of \$	
A check in t	he amount of \$		to cover	the filing fee is e	nclosed.
		by authorized t	o charge and	credit Deposit A	ccount No04-1073
as describe					
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x Credit a			on processing f	ees required unde	er 37 CFR 1.16 and 1.17

Attorney Reg. No.: -28.371-33.08Z

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(PATENT)

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### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of:

Kevin J. Torek et al.

Application No.: 09/643,946

Group Art Unit: 1765

Filed: August 23, 2000

Examiner: L. Vinh

For: ACID BLEND FOR REMOVING ETCH

RESIDUE

## AMENDMENT UNDER 37 C.F.R. § 1.116

ATTN: Box AF

Commissioner for Patents Washington, DC 20231

Dear Sir:

In response to the final Office Action dated January 16, 2002 (Paper No. 7), please amend the above-captioned application as follows:

### In the Claims:

Replace claims 142, 150 and 158 with amended claims 142, 150 and 158 below.

1\\dagged 2. (Twice Amended) A conditioning solution for use in removing residues remaining on a semiconductor substrate after a dry etch process, said conditioning solution comprising:

hydrofluòric acid;

phosphoric axid;

propylene glycoly and

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